

CLAIMS

1. A semiconductor device comprising:
- a first conductor including a first terminal surface;
  - 5 a second conductor placed by the first conductor and including a second terminal surface facing a same direction as does the first terminal surface;
  - a third conductor connected with the first conductor;
  - a semiconductor chip including a first surface and
  - 10 a second surface away from the first surface, the first surface being provided with a first electrode electrically connected with the first conductor via the third conductor, the second surface being provided with a second electrode electrically connected directly with
  - 15 the second conductor, the semiconductor chip being bonded to the first conductor and the second conductor via the second surface; and
  - a resin package sealing the first conductor, the second conductor, the third conductor and the
  - 20 semiconductor chip while exposing the first terminal surface and the second terminal surface.

2. The semiconductor device according to Claim 1, wherein the third conductor includes a first portion
- 25 connected with the first electrode and bonded to the first surface, and a second portion generally vertical to the first portion and connected with the first conductor.

3. The semiconductor device according to Claim 2, wherein the first portion of the third conductor entirely covers the first surface of the semiconductor chip.

5 4. A method of making a semiconductor device, using a lead frame including a semiconductor device formation area formed with a first conductor land and a second conductor land, the first conductor land having a first terminal surface, the second conductor land being by the  
10 first conductor land and having a second terminal surface facing in a same direction as does the first terminal surface, the method comprising:

a step of placing a semiconductor chip including a first surface formed with a first electrode and a second  
15 surface facing away from the first surface and formed with a second electrode, on the first conductor land and the second conductor land, via the second surface;

a step of placing a third conductor so as to contact the first conductor land and the first surface of the  
20 semiconductor chip;

a step of electrically connecting between the first conductor land and the third conductor, between the second electrode of the semiconductor chip and the second conductor land, and between the first electrode of the  
25 semiconductor chip and the third conductor;

a step of sealing the first conductor, the second conductor, the third conductor and the semiconductor chip with a resin package while exposing the first terminal

surface and the second terminal surface; and

a step of cutting the first conductor land and the second conductor land from the lead frame.

5 5. A semiconductor device comprising:

a first conductor including a first terminal surface;

a second conductor placed by the first conductor and including a second terminal surface facing in a same direction as does the first terminal surface;

10 a third conductor connected with the first conductor;

a semiconductor chip including a first surface and a second surface away from the first surface, the first surface being provided with a first electrode electrically connected with the first conductor via the  
15 third conductor, the second surface being provided with a second electrode electrically connected directly with the second conductor, the semiconductor chip being bonded to the first conductor and the second conductor via the second surface; and

20 a resin package sealing the first conductor, the second conductor, the third conductor and the semiconductor chip while exposing the first terminal surface and the second terminal surface;

wherein the first conductor has a first thin portion  
25 opposed to the second conductor and receded toward the first terminal surface, and

wherein the second conductor has a second thin portion opposed to the first conductor and receded from the second







a step of placing a semiconductor chip on the first portion of the first conductor land, or on the second conductor land;

a step of overlapping the first region and the second region with each other, via the semiconductor chip;

a step of electrically connecting between the first portion of the first conductor land and the semiconductor chip and between the second conductor land and the semiconductor chip;

a step of sealing the first conductor, the second conductor and the semiconductor chip with a resin package while exposing the first terminal surface and the second terminal surface; and

a step of cutting the first conductor land and the second conductor land from the lead frame;

wherein the third portion is smaller than the first portion in width at the first border region, or the third portion is smaller than the second portion in width at the second border region.

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13. The method according to Claim 12, wherein the folding of the first conductor land in the step of folding the first conductor land leaves the second portion to extend from the third portion in a direction away from the first portion.

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14. The method according to Claim 12, wherein the second portion includes a pair of projections each

